**UHF PLATE 2570**

**robust UHF TAG on metal**
- passive RFID UHF band, EPC Class1 Gen2
- black stainless steel plate with RFID dot
- optional: 2D laser print, graphic printing, deep laser print
- EEPROM memory
- mounting with cable ties or metal bands
- using under very harsh environmental conditions
- especially designed for asset management of metal and non-metal objects

These transponder device is an integral part of microsensys iID® system solutions.

**RFID Technology:** far field RFID system iID®4000, based on ISO 18000-6c, EPC Class1 Gen2
  - ALIEN HIGGS 3 or IMPINJ M4

**Chip Types:**
- ALIEN HIGGS 3
- IMPINJ M4

**Frequency Range:** 860-928MHz

**Minimum Operating Power:** -18 dBm

**Polarisation:** linear

**Communication Rate:**
- forward link: 40-160kBit/s
- return link: 40-640kBit/s

**Communication Distance:**
- 0 ... 1m on non-metal
- 0 ... 1m on metal

**Memory:** EEPROM

**Memory Capacity:**
- standard 512 bit user memory, 96 bit EPC memory, 64 bit TID memory

**Special Functionality:** see chip manufacture data sheet

**Operating Temperature:** -40°C ... +85°C

**Storage Temperature:** -45°C ... +125°C

**up to 200°C on inquiry**

**Dimensions:** approx. 25 x 70mm², thickness stainless steel 0.5mm, RFID dot thickness max. 4.0mm

**Packaging Material:**
- high quality stainless steel plate, RFID dot packaged in PEEK / Epoxy

**Mounting Instructions:**
- with cable tie or metal bands on metal or non metal objects
- uniform bending in the transverse direction possible, minimum R150mm

**Marking:** laser printing
- optional: customized graphic laser printing, bar code or 2D code laser printing,
  deep laser printed running number, electronic initializing

**Appropriate RFID Reader:**
- POCKETwork UHF
- CASIO IT-800 UHF
- INDUSTRY 0906 UHF
- others possible

**HOST Command Set:** see actual API documentation of microsensys iID® driver engine

**Type:**
- 16.921.453.00
- 16.932.453.00

**Chip Type:**
- ALIEN HIGGS 3
- IMPINJ M4

**Memory:**
- 512 (user) bit

**Data Retention:**
- 50 years

**Communication Distance:**
- 1 m

---

© microsensys, mi3, iID and TELID are registered trademarks or trademarks of microsensys GmbH. Other products mentioned in this document may be trademarks of microsensys or trademarks or registered trademarks of other software, hardware, or service providers and are used herein for identification purposes only. Windows and the Windows Logo are trademarks or registered trademarks of Microsoft Corporation in the United States and/or other countries.